74LVC244A; 74LVCH244A

Octal buffer/line driver; 3-state

Rev. 8 — 26 June 2013 Product data sheet

1. General description

The 74LVC244A; 74LVCH244A is an octal non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs $1\overline{OE}$ and $2\overline{OE}$. A HIGH on $n\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Schmitt-trigger action at all inputs makes the circuit highly tolerant for slower input rise and fall times.

Inputs can be driven from either 3.3 V or 5.0 V devices. In 3-state operation, outputs can handle 5 V. These features allow the use of these devices as translators in a mixed 3.3 V and 5 V environment.

The 74LVCH244A bus hold on data inputs eliminates the need for external pull-up resistors to hold unused inputs.

2. Features and benefits

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low-power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- High-impedance when V_{CC} = 0 V
- Bus hold on all data inputs (74LVCH244A only)
- Complies with JEDEC standard:
  - JESD8-7A (1.65 V to 1.95 V)
  - JESD8-5A (2.3 V to 2.7 V)
  - JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115B exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Specified from −40 °C to +85 °C and −40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC244AD	−40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74LVCH244AD				
74LVC244ADB	−40 °C to +125 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74LVCH244ADB				
74LVC244APW	−40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74LVCH244APW				
74LVC244ABQ	−40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
74LVCH244ABQ				
74LVC244ABX	−40 °C to +125 °C	DHXQFN20	plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; body 4.5 × 2.5 × 0.5 mm	SOT1045-2
74LVCH244ABX				

4. Functional diagram

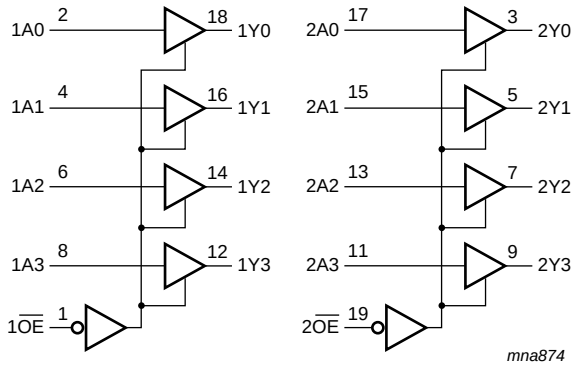


Fig 1. Logic symbol

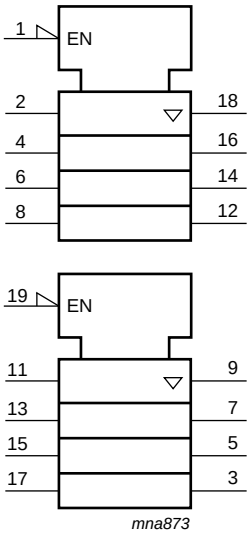


Fig 2. IEC logic diagram

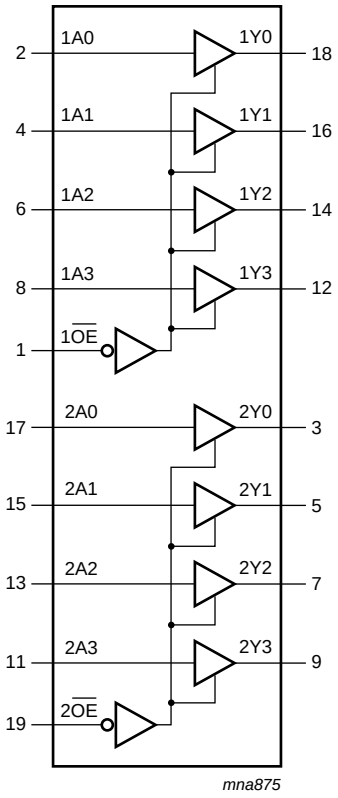


Fig 3. Functional diagram

5. Pinning information

5.1 Pinning

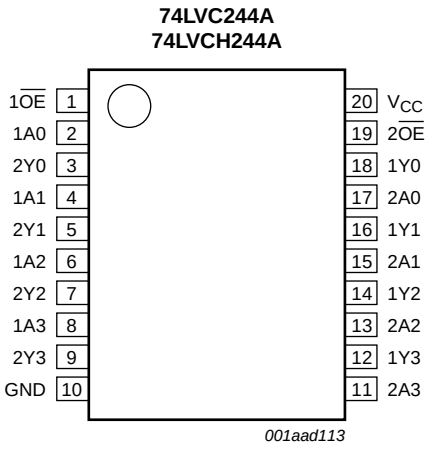
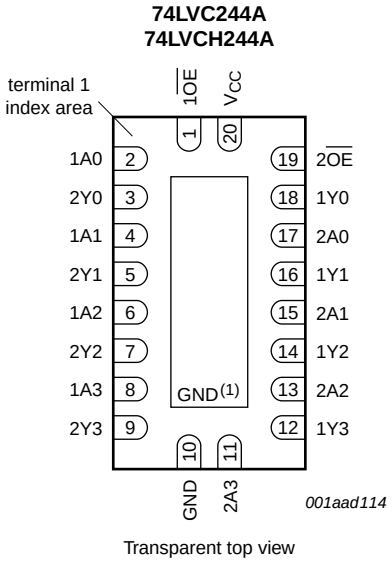


Fig 4. Pin configuration for SO20 and (T)SSOP20



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration for DHVQFN20 and DHXQFN20

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$1\overline{OE}$, $2\overline{OE}$	1, 19	output enable input (active low)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	data output
GND	10	ground (0 V)
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3,	18, 16, 14, 12	data output
V_{CC}	20	supply voltage

6. Functional description

Table 3. Function table [1]

Control	Input	Output
$\overline{nOE}$	nAn	nYn
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V		–50	-	mA
V_I	input voltage		[1]	–0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V		-	±50	mA
V_O	output voltage	output HIGH or LOW	[2]	–0.5	V_{CC} + 0.5	V
		output 3-state	[2]	–0.5	+6.5	V
I_O	output current	V_O = 0 V to V_{CC}		-	±50	mA
I_{CC}	supply current			-	100	mA
I_{GND}	ground current			–100	-	mA
T_{stg}	storage temperature			–65	+150	°C
P_{tot}	total power dissipation	T_{amb} = –40 °C to +125 °C	[3]	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO20 packages: above 70 °C derate linearly with 8 mW/K.
For (T)SSOP20 packages: above 60 °C derate linearly with 5.5 mW/K.
For DHVQFN20 and DHXQFN20 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	3.6	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	output HIGH or LOW	0	-	V_{CC}	V
		output 3-state	0	-	5.5	V
T_{amb}	ambient temperature	in free air	–40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 1.2 V to 2.7 V	0	-	20	ns/V
		V_{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
V_{IH}	HIGH-level input voltage	V_{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}	-	-	0.65 × V_{CC}	-	V
		V_{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V_{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V_{CC} = 1.65 V to 1.95 V	-	-	0.35 × V_{CC}	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V_{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = –100 μA; V_{CC} = 1.65 V to 3.6 V	V_{CC} – 0.2	-	-	V_{CC} – 0.3	-	V
		I_O = –4 mA; V_{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I_O = –8 mA; V_{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I_O = –12 mA; V_{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I_O = –18 mA; V_{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I_O = –24 mA; V_{CC} = 3.0 V	2.2	-	-	2.0	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = 100 μA; V_{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I_O = 4 mA; V_{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I_O = 8 mA; V_{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I_O = 12 mA; V_{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I_O = 24 mA; V_{CC} = 3.0 V	-	-	0.55	-	0.8	V

Table 6. Static characteristics *…continued*

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
I_I	input leakage current	V_I = 5.5 V or GND; V_{CC} = 3.6 V	[2]	-	±0.1	±5	-	±20	µA
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL}; V_O = 5.5 V or GND; V_{CC} = 3.6 V	[2]	-	±0.1	±5	-	±20	µA
I_{OFF}	power-off leakage current	V_I or V_O = 5.5 V; V_{CC} = 0.0 V		-	±0.1	±10	-	±20	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 3.6 V		-	0.1	10	-	40	µA
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC}$ – 0.6 V; I_O = 0 A; V_{CC} = 2.7 V to 3.6 V		-	5	500	-	5000	µA
C_I	input capacitance			-	4.0	-	-	-	pF
I_{BHL}	bus hold LOW current	V_{CC} = 1.65 V; V_I = 0.58 V	[3][4]	10	-	-	10	-	µA
		V_{CC} = 2.3 V; V_I = 0.7 V		30	-	-	25	-	µA
		V_{CC} = 3.0 V; V_I = 0.8 V		75	-	-	60	-	µA
I_{BHH}	bus hold HIGH current	V_{CC} = 1.65 V; V_I = 1.07 V	[3][4]	–10	-	-	–10	-	µA
		V_{CC} = 2.3 V; V_I = 1.7 V		–30	-	-	–25	-	µA
		V_{CC} = 3.0 V; V_I = 2.0 V		–75	-	-	–60	-	µA
I_{BHLO}	bus hold LOW overdrive current	V_{CC} = 1.95 V	[3][5]	200	-	-	200	-	µA
		V_{CC} = 2.7 V		300	-	-	300	-	µA
		V_{CC} = 3.6 V		500	-	-	500	-	µA
I_{BHHO}	bus hold HIGH overdrive current	V_{CC} = 1.95 V	[3][5]	–200	-	-	–200	-	µA
		V_{CC} = 2.7 V		–300	-	-	–300	-	µA
		V_{CC} = 3.6 V		–500	-	-	–500	-	µA

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

[2] The bus hold circuit is switched off when $V_I > V_{CC}$ allowing 5.5 V on the input terminal.

[3] Valid for data inputs of bus hold parts only (74LVCH244A). Note that control inputs do not have a bus hold circuit.

[4] The specified sustaining current at the data input holds the input below the specified V_I level.

[5] The specified overdrive current at the data input forces the data input to the opposite input state.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 8.

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nAn to nYn; see Figure 6	[2]						
		V_{CC} = 1.2 V		-	17.0	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V		1.5	6.4	13.7	1.5	15.8	ns
		V_{CC} = 2.3 V to 2.7 V		1.0	3.4	7.1	1.0	8.2	ns
		V_{CC} = 2.7 V		1.5	3.4	6.9	1.5	9.0	ns
		V_{CC} = 3.0 V to 3.6 V		1.5	2.9	5.9	1.5	7.5	ns
t_{en}	enable time	$n\overline{OE}$ to nYn; see Figure 7	[2]						
		V_{CC} = 1.2 V		-	24.0	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V		1.5	7.0	17.3	1.5	20.0	ns
		V_{CC} = 2.3 V to 2.7 V		1.5	3.9	9.5	1.5	11.0	ns
		V_{CC} = 2.7 V		1.5	4.1	8.6	1.5	11.0	ns
		V_{CC} = 3.0 V to 3.6 V		1.0	3.2	7.6	1.0	9.5	ns
t_{dis}	disable time	$n\overline{OE}$ to nYn; see Figure 7	[2]						
		V_{CC} = 1.2 V		-	9.0	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V		2.2	4.5	9.8	2.2	11.3	ns
		V_{CC} = 2.3 V to 2.7 V		0.5	3.6	5.5	0.5	6.4	ns
		V_{CC} = 2.7 V		1.5	3.3	6.8	1.5	8.5	ns
		V_{CC} = 3.0 V to 3.6 V		1.5	3.1	5.8	1.5	7.5	ns
$t_{sk(o)}$	output skew time		[3]	-	-	1.0	-	1.5	ns
C_{PD}	power dissipation capacitance	per input; V_I = GND to V_{CC}	[4]						
		V_{CC} = 1.65 V to 1.95 V		-	6.4	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V		-	9.6	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V		-	12.5	-	-	-	pF

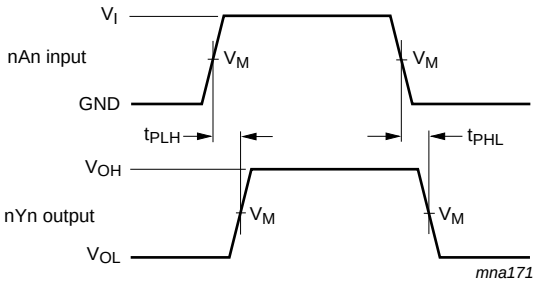
[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz; f_o = output frequency in MHz
C_L = output load capacitance in pF
V_{CC} = supply voltage in Volts
N = number of inputs switching
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

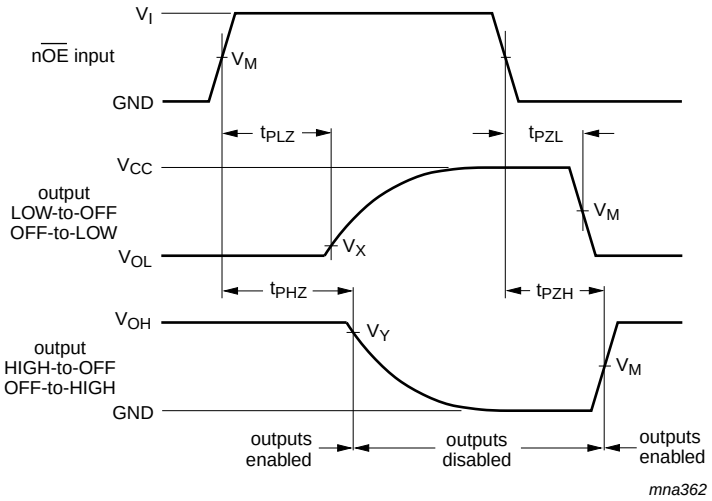
11. AC waveforms



Measurement points are given in Table 8.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. The input (nAn) to output (nYn) propagation delays



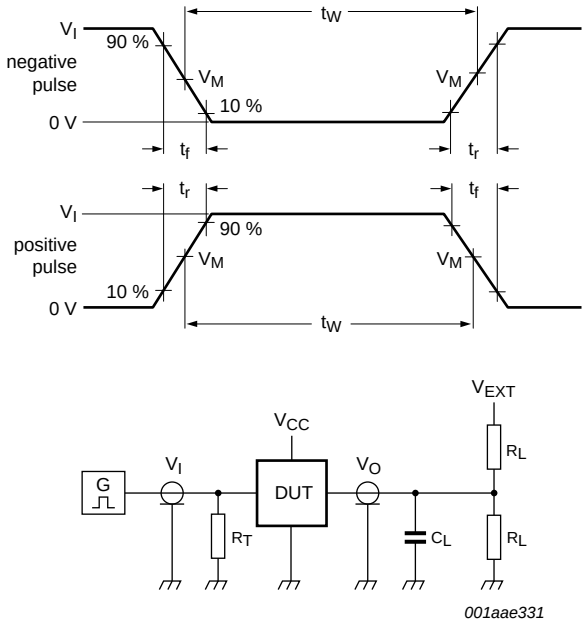
Measurement points are given in Table 8.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. 3-state enable and disable times.

Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
1.2 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
1.65 V to 1.95 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
2.3 V to 2.7 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
2.7 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V



Test data is given in Table 9.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

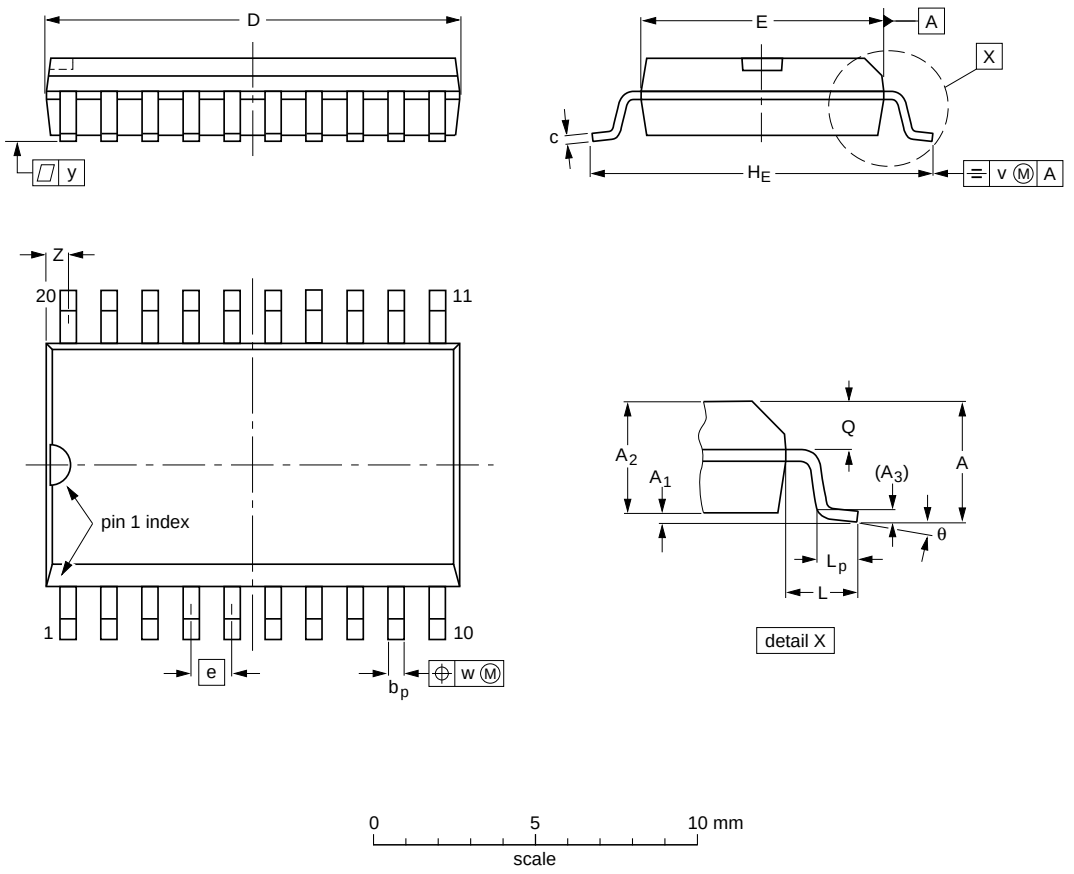
Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ	open	2 × V_{CC}	GND
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ	open	2 × V_{CC}	GND
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω	open	2 × V_{CC}	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V_{CC}	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V_{CC}	GND

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

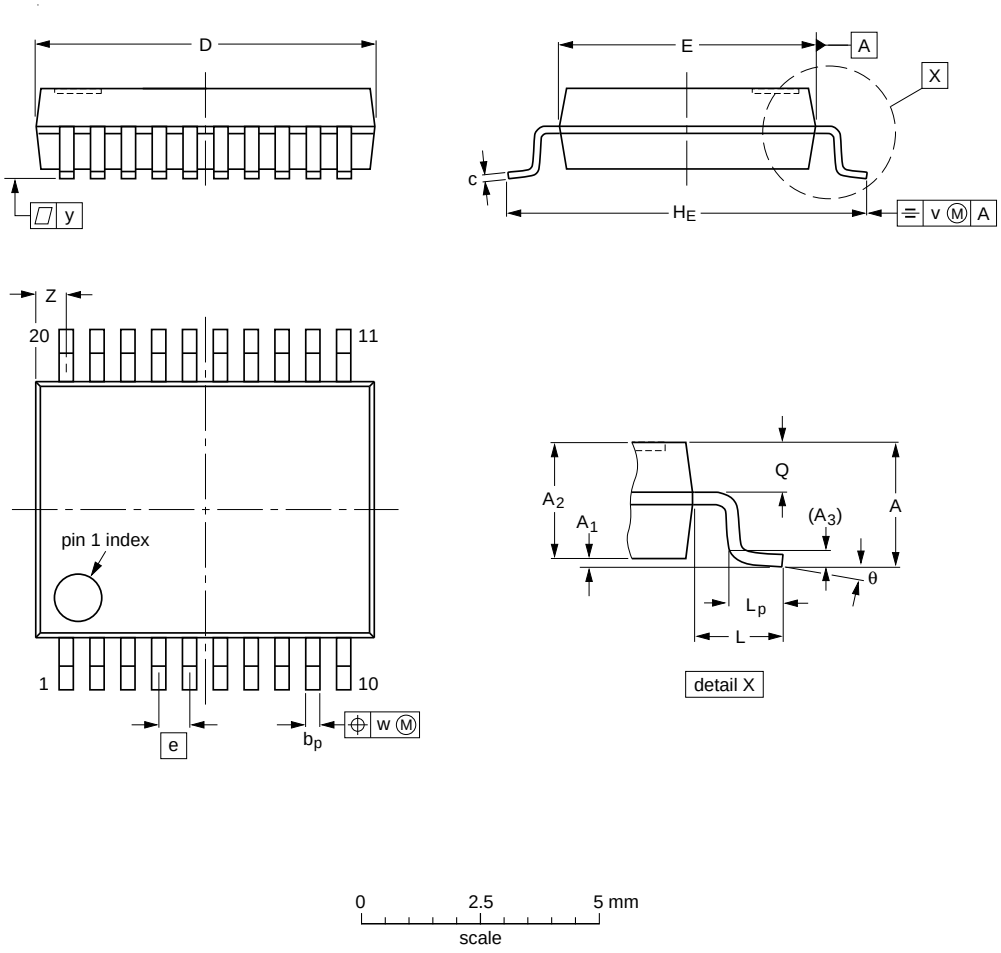
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8^o 0^o

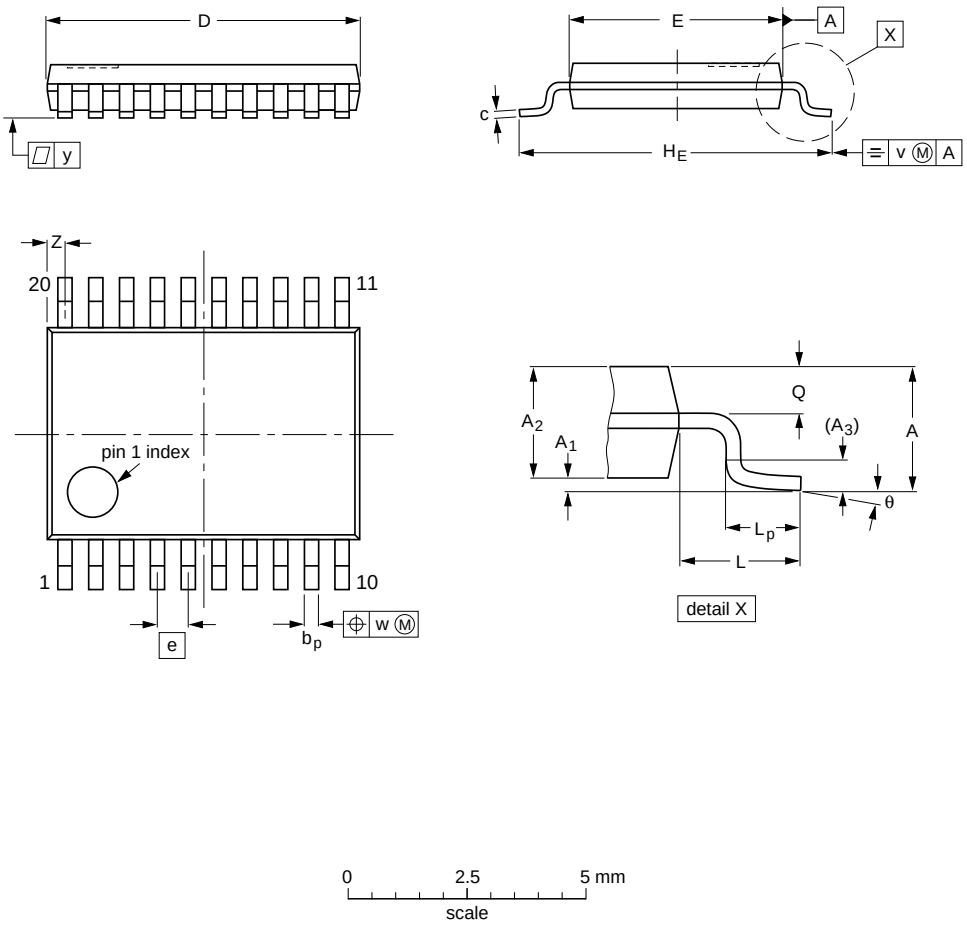
Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT339-1		MO-150				~~99-12-27~~ 03-02-19

Fig 10. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

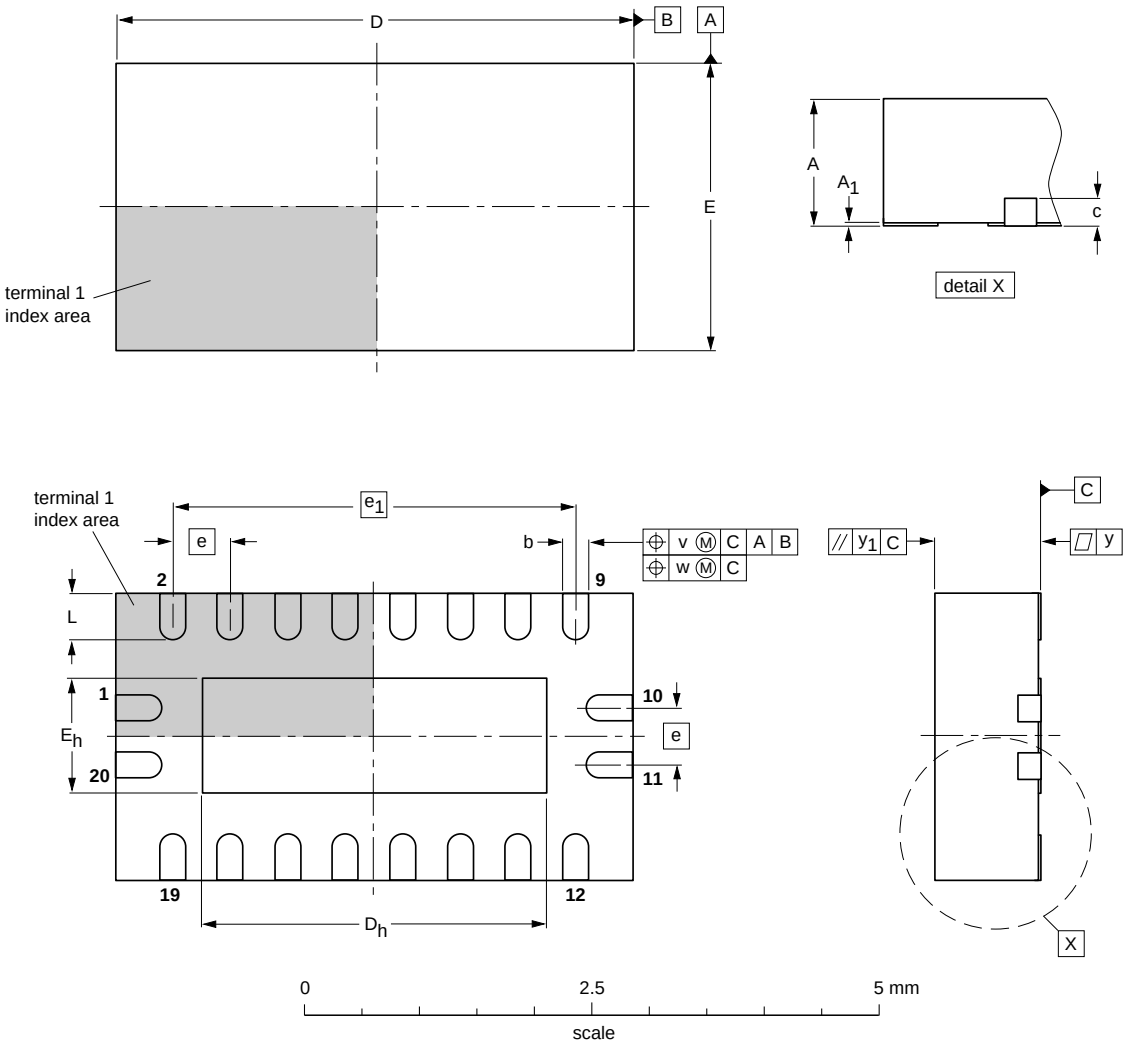
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 11. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm **SOT764-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.6 4.4	3.15 2.85	2.6 2.4	1.15 0.85	0.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

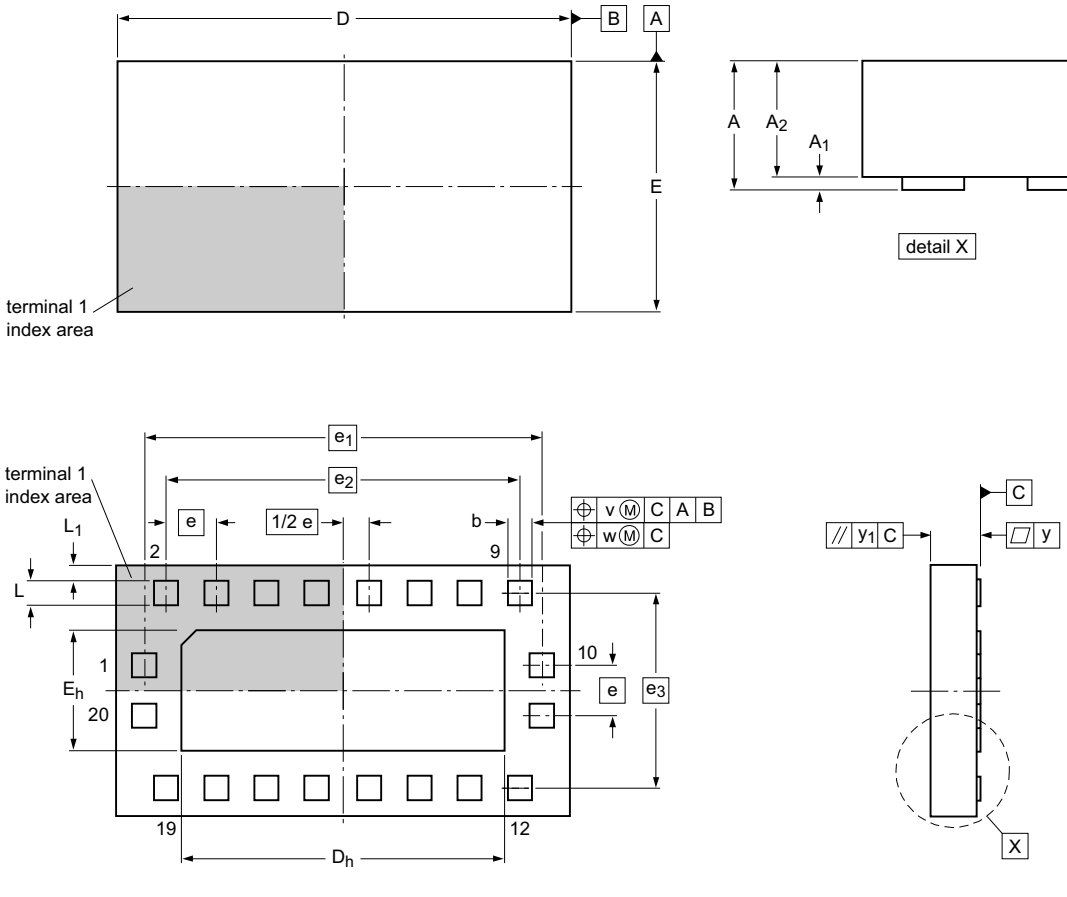
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT764-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

Fig 12. Package outline SOT764-1 (DHVQFN20)

DHXQFN20: plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; body 4.5 x 2.5 x 0.5 mm

SOT1045-2



Dimensions

Unit		A	A_1	A_2	b	L	D	D_h	E	E_h	L_1	e	e_1	e_2	e_3	v	w	y_1	y
mm	max	0.50	0.08	0.42	0.30	0.29	4.55	3.30	2.55	1.30	0.20								
	nom		0.05	0.40	0.25	0.24	4.50	3.20	2.50	1.20	0.15	0.5	3.95	3.5	1.95	0.1	0.05	0.1	0.08
	min		0.02	0.38	0.20	0.19	4.45	3.10	2.45	1.10	0.10								

sot1045-2_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1045-2						~~11-08-11~~ 11-08-18

Fig 13. Package outline SOT1045-2 (DHXQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC_LVCH244A v.8	20130626	Product data sheet	-	74LVC_LVCH244A v.7
Modifications:	• For type numbers 74LVC244ABX and 74LVCH244ABX DHXQFN20U (SOT1045-1) has changed to DHXQFN20 (SOT1045-2).			
74LVC_LVCH244A v.7	20111122	Product data sheet	-	74LVC_LVCH244A v.6
Modifications:	• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 4, Table 5, Table 6, Table 7, Table 8 and Table 9: values added for lower voltage ranges.			
74LVC_LVCH244A v.6	20090813	Product data sheet	-	74LVC_LVCH244A v.5
74LVC_LVCH244A v.5	20090709	Product data sheet	-	74LVC_LVCH244A v.4
74LVC_LVCH244A v.4	20031030	Product specification	-	74LVC_LVCH244A v.3
74LVC_LVCH244A v.3	20030520	Product specification	-	74LVC_H244A v.2
74LVC_H244A v.2	19980520	Product specification	-	74LVC244A_74LVCH244A v.1
74LVC244A_74LVCH244A v.1	19960906	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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